

AMENDMENTS TO THE CLAIMS, COMPLETE LISTING OF CLAIMS
IN ASCENDING ORDER WITH STATUS INDICATOR

Please amend the following claims as indicated.

1. (Currently Amended) A conductive particle comprising:
a base particle;
core materials disposed on the surface of the base particle to form projections on the outer surface of the base particle; and
a conductive film or conductive films covering the surface of said base particle and said core materials, such that said projections are formed by said core materials;
~~wherein projections are formed on the outer surface of the conductive film or conductive films; and~~
wherein the core materials are composed of a conductive material different from a conductive material composing said conductive film or conductive films.
2. (Previously Presented) The conductive particle according to claim 1, wherein each of said core materials has a shape in lump form.
3. (Previously Presented) The conductive particle according to claim 1 or 2, wherein the outermost surface of said conductive film is a gold layer.
4. (Currently Amended) A conductive particle comprising:
a base particle;
core materials disposed on the surface of the base particle to form projections on the outer surface of the base particle ~~and made of a conductive material~~; and
a plated coat covering the surface of said base particle and said core materials, such that said projections are formed by said core materials;
~~wherein projections are formed on the outer surface of said plated coat~~

wherein said core materials are made of a conductive material.

5. (Previously Presented) The conductive particle according to claim 4, wherein at least 80% or more of said core materials existing on the surface of said base particle contacts with said base particle or exists within a range of 5 nm from said base particle.

6. (Previously Presented) The conductive particle according to claim 4 or 5, wherein the outermost surface of said plated coat is a gold layer.

7. (Previously Presented) The conductive particle according to claim 1 or 4, wherein said core materials are composed of at least one or more species of metal.

8. (Previously Presented) The conductive particle according to claim 1 or 4, wherein said base particle is a resin particle.

9. (Previously Presented) The conductive particle according to claim 1 or 4, wherein an average height of said projections projecting is 0.5% or more of an average particle diameter of said conductive particle.

10. (Previously Presented) An anisotropic conductive material comprising a resin binder and the conductive particle according to claim 1 or 4 dispersed in said resin binder.